

PRELIMINARY DATA SHEET

SKY77518 TX-RX iPAC™ FEM for Dual-Band GSM/GPRS

Applications

- Dual-band cellular handsets encompassing
 - Class 4 GSM900
 - DCS1800
 - Class 12 GPRS multi-slot operation

Features

- High efficiency
 - GSM900 48%
 - DCS 41%
- Low transmit supply current
 - GSM900 1.26 A
 - DCS1800 0.9 A
- Internal ICC sense resistor for iPAC
- Closed loop iPAC
- 50 Ω matched Input/Output
- TX-VCO-to-antenna and antenna-to-Rx-SAW filter RF interface
- TX harmonics below -33 dBm
- PHEMT RF switches afford high linearity, low insertion loss, and less than 20 μA supply current in receive modes
- Small outline: 6 mm x 8 mm
- Low profile: 1.2 mm
- Compatible with multiple logic families
- Low APC current: 25 μA
- Gold plated, lead free contacts

NEW Skyworks offers lead (Pb)-free "environmentally friendly" packaging that is RoHS compliant (European Parliament for the Restriction of Hazardous Substances).



Description

The SKY77518 is a transmit and receive front-end module (FEM) with Integrated Power Amplifier Control (iPAC™) for dual-band cellular handsets comprising GSM900 and DCS1800 operation. Designed in a low profile, compact form factor, the SKY77518 offers a complete Transmit VCO-to-Antenna and Antenna-to-Receive SAW filter solution. The FEM also supports Class 12 General Packet Radio Service (GPRS) multi-slot operation.

The module consists of a GSM900 PA block and a DCS1800 PA block, impedance-matching circuitry for 50 Ω input and output impedances, TX harmonics filtering, high linearity and low insertion loss PHEMT RF switches, diplexer and a Power Amplifier Control (PAC) block with internal current sense resistor. A custom BiCMOS integrated circuit provides the internal PAC function and decoder circuitry to control the RF switches. The two Heterojunction Bipolar Transistor (HBT) PA blocks are fabricated onto a single Gallium Arsenide (GaAs) die. One PA block supports the GSM900 band and the other PA block supports the DCS1800 band. Both PA blocks share common power supply pads to distribute current. The output of each PA block and the outputs to the two receive pads are connected to the antenna pad through PHEMT RF switches and a diplexer. The GaAs die, PHEMT die, Silicon (Si) die and passive components are mounted on a multi-layer laminate substrate. The assembly is encapsulated with plastic overmold.

Band selection and control of transmit and receive modes are performed using two external control pads. Refer to the functional block diagram in Figure 1 below. The band select pad (BS) selects between GSM and DCS modes of operation. The transmit enable (TX_EN) pad controls receive or transmit mode of the respective RF switch (TX = logic 1). Proper timing between transmit enable (TX_EN) and Analog Power Control (VRAMP) allows for high isolation between the antenna and TX-VCO while the VCO is being tuned prior to the transmit burst.

The SKY77518 is compatible with logic levels from 1.2 V to VCC for BS and TX_EN pads, depending on the level applied to the VLOGIC pad. This feature provides additional flexibility for the designer in the selection of FEM interface control logic.

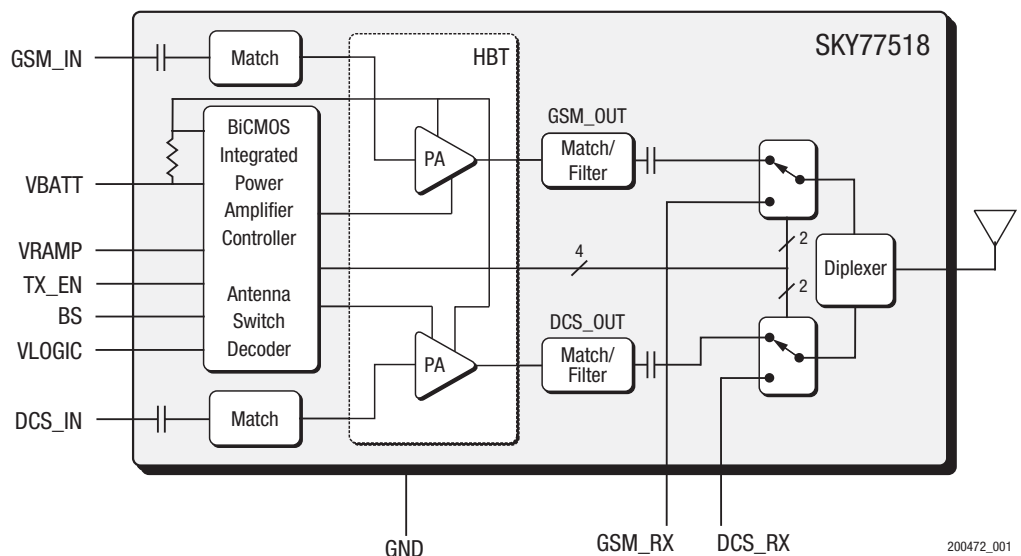


Figure 1. Functional Block Diagram

Electrical Specifications

The following tables list the electrical characteristics of the SKY77518 Front-End Module. The absolute maximum ratings and recommended operating conditions for the SKY77518 are listed in [Table 1](#) and [Table 2](#), respectively. [Table 3](#) specifies the mode control logic and [Table 4](#) contains the electrical characteristics of

the SKY77518 for modes GSM900 and DCS1800. [Figure 2](#) presents an application schematic for the SKY77518.

The SKY77518 is a static-sensitive electronic device and should not be stored or operated near strong electrostatic fields. Detailed information on device dimensions, pad descriptions, packaging and handling can be found in later sections of this data sheet.

Table 1. Absolute Maximum Ratings

Parameter	Minimum	Maximum	Unit
Input Power (P _{IN})	—	15	dBm
Supply Voltage (V _{CC}), Standby V _{RAMP} ≤ 0.3 V V _{LOGIC} ≤ 0.5 V	—	7	V
Control Voltage (V _{RAMP})	-0.5	V _{CC_MAX} - 0.2 V (See Table 4)	V
Storage Temperature	-55	+150	°C

Table 2. Recommended Operating Conditions

Parameter	Minimum	Typical	Maximum	Unit
Supply Voltage (V _{CC})	2.7	3.3	4.8	V
Supply Current (I _{CC})	0		1.8	A
Operating Case Temperature (T _{CASE}) ¹ 1-Slot (12.5% duty cycle) 2-Slot (25% duty cycle)	-20 -20		+85 +85	°C

¹ Case Operating Temperature refers to the temperature of the GROUND PAD on the underside of the package.

Table 3. SKY77518 Mode Control Logic

Mode	V _{LOGIC}	Input Control Bits	
		TX_En	BS
STANDBY	0	X 1	X 1
GSM_Rx	1	0	0
DCS_Rx	1	0	1
GSM_TX	1	1	0
DCS_TX	1	1	1

¹ X = don't care

Table 4. SKY77518 Electrical Specifications¹ (1 of 5)

General							
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units	
Supply voltage	VCC	—	2.7	3.3	4.8	V	
Power control impedance	ZVRAMP	—		300		kΩ	
VLOGIC control voltage	LOW HIGH	VLOGIC_LOW VLOGIC_HIGH	— 1.2	— —	0.5 VCC	V	
VLOGIC current	IVLOGIC	VLOGIC ≤ 2.7 V TX_EN ≤ 0.4 V BS ≤ 0.4 V	—	1	20	μA	
Band Select control voltage	LOW HIGH	VBS_LOW VBS_HIGH	— —	— —	30% VLOGIC VLOGIC	V	
Band Select current	IBS	BS ≤ 2.7 V	—	8	20	μA	
TX_EN control voltage	LOW HIGH	VTX_EN_LOW VTX_EN_HIGH	— —	— —	30% VLOGIC VLOGIC	V	
TX_EN current	ITX_EN	TX_EN ≤ 2.7 V	—	8	20	μA	
Leakage current	Standby Mode	Ios	VCC ≤ 4.8 V VLOGIC = VLOGIC_LOW VRAMP ≤ 0.1 V TX_EN ≤ 0.4 V BS ≤ 0.4 V BS ≥ VLOGIC - 0.4 V TCASE = +25 °C PIN ≤ -60 dBm	—	2	10	μA
	Receive Mode	IQRX	VCC ≤ 4.8 V 1.2 V ≤ VLOGIC ≤ 2.7 V VRAMP ≤ 0.1 V TX_EN ≤ 0.4 V BS ≤ 0.4 V BS ≥ VLOGIC - 0.4 V TCASE = +25 °C PIN ≤ -60 dBm	—	15	50	

Table 4. SKY77518 Electrical Specifications¹ (2 of 5)

GSM900 Mode (f = 880 to 915 MHz and P _{IN} = 0 to 6 dBm)						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Frequency range	f	—	880	—	915	MHz
Input power	P _{IN}	—	0	—	6	dBm
Analog power control voltage	V _{RAMP}	—	0.2	—	1.8	V
Power Added Efficiency	PAE	V _{CC} = 3.3 V P _{OUT} = 33 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 33 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = +25 °C	41	48	—	%
Supply Current @ Rated Power	I _{CC_33 dBm}	V _{CC} = 3.3 V P _{OUT} = 33 dBm P _{IN} = 3 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 33 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = +25 °C	—	1.26	1.48	A
Supply Current @ Minimum Power	I _{CC_5 dBm}	V _{CC} = 3.3 V P _{OUT} = 5 dBm P _{IN} = 3 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 5 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = +25 °C	—	53	60	mA
Harmonics	2nd to 13th	2f _o to 13f _o BW = 3 MHz 5 dBm ≤ P _{OUT} ≤ 33 dBm V _{RAMP} controlled ⁶	—	-40	-33	dBm
Output power	P _{OUT}	V _{CC} = 3.3 V T _{CASE} = +25 °C P _{IN} = 0 dBm	33.0	33.5	—	dBm
	P _{OUT_MAX LOW VOLTAGE}	V _{CC} = 2.7 V TX_EN = V _{TX_EN_HIGH} T _{CASE} = -20 °C to +85 °C P _{IN} = 0 dBm	30.5	31.5	—	
	P _{OUT_MAX HIGH VOLTAGE}	V _{CC} = 4.8 V TX_EN = V _{TX_EN_HIGH} T _{CASE} = -20 °C to +85 °C P _{IN} = 0 dBm	30.5	34.5	—	
Input VSWR	Γ _{IN}	P _{OUT} = 5 to 33 dBm V _{RAMP} controlled ⁶	—	1.5:1	2.5:1	
Forward isolation ⁴	P _{OUT_RX}	P _{IN} = 6 dBm V _{RAMP} ≤ 0.1 V V _{LOGIC} = V _{LOGIC_HIGH} TX_EN = V _{TX_EN_LOW} Mode = GSM_Rx (see Table 3)	—	-65	-45	dBm
	P _{OUT_ENABLED_TX}	P _{IN} = 6 dBm V _{RAMP} ≤ 0.1 V V _{LOGIC} = V _{LOGIC_HIGH} TX_EN = V _{TX_EN_HIGH} Mode = GSM_TX (see Table 3)	—	-40	-5	
Coupling of GSM900 TX output (f ₀) to GSM_Rx output pad ⁴	CGHI_TX-Rx_F0	5 dBm ≤ P _{OUT} ≤ 33 dBm Mode = GSM_TX (see Table 3)	—	3	11	dBm
Coupling of GSM900 TX output (2f ₀ , 3f ₀) to DCS/PCS_Rx output pad	CGHI_TX-DCS_Rx	5 dBm ≤ P _{OUT} ≤ 33 dBm Mode = GSM_TX (see Table 3)	—	-50	-36	dBm

Table 4. SKY77518 Electrical Specifications ¹ (3 of 5)

GSM900 Mode (f = 880 to 915 MHz and P _{IN} = 0 to 6 dBm) [continued]						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Spurious	Spur	All combinations of the following parameters: V _{RAMP} = controlled ² P _{IN} = min. to max. V _{CC} = 2.7 V to 4.8 V Load VSWR = 12:1, all phase angles	No parasitic oscillation > -36 dBm			
Load mismatch	Load	All combinations of the following parameters: V _{RAMP} = controlled ² P _{IN} = min. to max. V _{CC} = 2.7 V to 4.8 V Load VSWR = 20:1, all phase angles	No module damage or permanent degradation			
Rx Band Spurious	Rx_SPUR	At f _o + 20 MHz (935 to 960 MHz) RBW = 100 kHz V _{CC} = 3.3 V 5 dBm ≤ P _{OUT} ≤ 33 dBm T _{CASE} = +25 °C	—	-84	-82	dBm
		At f _o + 10 MHz (925 to 935 MHz) RBW = 100 kHz V _{CC} = 3.3 V T _{CASE} = +25 °C 5 dBm ≤ P _{OUT} ≤ 33 dBm	—	-80	-76	
		At 1805 to 1880 MHz RBW = 100 kHz V _{CC} = 3.3 V T _{CASE} = +25 °C 5 dBm ≤ P _{OUT} ≤ 33 dBm	—	-101	-84	
Power control dynamic range	PCDR		30	50	—	dB
Power control variation	PCV	Control level 5-15 (V _{CC} ≥ 3.3 V) P _{OUT} 13 to 33 dBm, +25 °C	-1.0	—	1.0	dB
		Control level 16-19 P _{OUT} 13 to 33 dBm	-1.5	—	1.5	
Power control slope	PCs	P _{OUT} 5 to 11 dBm, +25 °C	-2.0	—	2.0	dB/V
		P _{OUT} 5 to 11 dBm	-3.5	—	3.5	
GSM900 RECEIVE (f = 925 to 960 MHz) Mode = GSM_Rx						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Frequency range	f	—	925	—	960	MHz
Insertion Loss, ANT to GSM_Rx ⁴	IL GSM_Rx	—	—	1.0	1.3	dB
VSWR ANT, GSM_Rx ⁴	Γ _{IN} , Γ _{OUT}	—	—	1.2:1	1.5:1	

Table 4. SKY77518 Electrical Specifications ¹ (4 of 5)

DCS1800 Mode (f = 1710 to 1785 MHz and P _{IN} = 0 to 6 dBm)							
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units	
Frequency range	f	—	1710	—	1785	MHz	
Input power	P _{IN}	—	0	—	6	dBm	
Analog power control voltage	V _{RAMP}	—	0.2	—	1.8	V	
Power Added Efficiency	PAE	V _{CC} = 3.3 V P _{OUT} = 31 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 31 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = +25 °C	35	41	—	%	
Supply Current @ Rated Power	I _{CC_31 dBm}	V _{CC} = 3.3 V P _{OUT} = 31 dBm P _{IN} = 3 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 31 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = +25 °C	—	0.93	1.04	A	
Supply Current @ Minimum Power	I _{CC_0 dBm}	V _{CC} = 3.3 V P _{OUT} = 0 dBm P _{IN} = 3 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 0 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = +25 °C	—	40	55	mA	
Harmonics	2 nd to 4 th , 7 th 5 th , 6 th	2f ₀ to 4f ₀ , 7f ₀	BW = 3 MHz, 0 dBm ≤ P _{OUT} ≤ 31 dBm V _{RAMP} controlled ⁵	—	-40	-33	dBm
		5f ₀ , 6f ₀		—	-35	-25	
Output power	P _{OUT}	V _{CC} = 3.3 V T _{CASE} = +25 °C P _{IN} = 0 dBm	31.0	32.0	—	dBm	
	P _{OUT_MAX LOW VOLTAGE}	V _{CC} = 2.7 V TX_EN = V _{TX_EN_HIGH} T _{CASE} = -20 °C to +85 °C P _{IN} = 0 dBm	28.5	30.0	—		
	P _{OUT_MAX HIGH VOLTAGE}	V _{CC} = 4.8 V TX_EN = V _{TX_EN_HIGH} T _{CASE} = -20 °C to +85 °C P _{IN} = 0 dBm	28.5	32.5	—		
Input VSWR	Γ _{IN}	P _{OUT} = 0 to 31 dBm V _{RAMP} controlled ⁵	—	1.5:1	2.5:1	—	
Forward isolation ⁴	P _{OUT_Rx}	P _{IN} = 6 dBm V _{RAMP} ≤ 0.1 V V _{LOGIC} = V _{TX_EN_HIGH} TX_EN = V _{TX_EN_LOW} Mode=DCS_Rx (see Table 3)	—	-65	-53	dBm	
	P _{OUT_ENABLED_TX}	P _{IN} = 6 dBm V _{RAMP} ≤ 0.1 V V _{LOGIC} = V _{LOGIC_HIGH} TX_EN = V _{TX_EN_HIGH} Mode = DCS_TX (see Table 3)	—	-35	-5		
Coupling of DCS TX output to Receive RF output pad ⁴	CDCS_TX-Rx_F0	0 dBm ≤ P _{OUT} ≤ 31 dBm Mode = DCS_TX (see Table 1)	—	2	9	dBm	

Table 4. SKY77518 Electrical Specifications ¹ (5 of 5)

DCS1800 Mode (f = 1710 to 1785 MHz and P _{IN} = 0 to 6 dBm) [continued]						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Spurious	Spur	All combinations of the following parameters: V _{RAMP} = controlled ³ P _{IN} = min. to max V _{CC} = 2.7 V to 4.8 V Load VSWR = 12:1, all phase angles	No parasitic oscillation > -36 dBm			
Load mismatch	Load	All combinations of the following parameters: V _{RAMP} = controlled ³ P _{IN} = min. to max. V _{CC} = 2.7 V to 4.8 V Load VSWR = 20:1, all phase angles	No module damage or permanent degradation			
Rx Band Spurious	RX_SPUR	At f ₀ + 20 MHz (1805 to 1880 MHz) RBW = 100 kHz V _{CC} = 3.3 V T _{CASE} = +25 °C 0 dBm ≤ P _{OUT} ≤ 31 dBm	—	-83	-78	dBm
		925 to 960 MHz RBW = 100 kHz V _{CC} = 3.3 V T _{CASE} = +25 °C 0 dBm ≤ P _{OUT} ≤ 31 dBm	—	—	-87	
Power control dynamic range	PCDR		35	50	—	dB
Power control variation	PCV	Control level 0-8 V _{CC} ≥ 3.3 V P _{OUT} 14 to 31 dBm, +25 °C	-1.5	—	1.5	dB
		P _{OUT} 14 to 31 dBm	-2.0	—	2.0	
		Control level 9-13 P _{OUT} 4 to 12 dBm, +25 °C	-2.5	—	2.5	
		P _{OUT} 4 to 12 dBm	-3.5	—	3.5	
Control level 14-15	PCs	P _{OUT} 0 to 2 dBm, +25 °C	-3.0	—	3.0	dB/V
		P _{OUT} 0 to 2 dBm	-4.5	—	4.5	
Power control slope	PCs	0 to 30 dBm	—	—	150	dB/V
DCS 1800 RECEIVE (f =1805 to 1880 MHz) Mode = DCS_Rx						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Frequency range	f	—	1805	—	1880	MHz
Insertion Loss, ANT to DCS_Rx ⁴	IL DCS_Rx	—	—	1.2	1.5	dB
VSWR ANT, DCS_Rx ⁴	Γ _{IN} , Γ _{OUT}	—	—	1.2:1	1.5:1	

¹ Unless specified otherwise:
T_{CASE} = -20 °C to max. operating temperature (see Table 2), RL = 50 Ω, pulsed operation with pulse width ≤ 1154 μs and duty cycle ≤ 2:8, V_{CC} = 2.7 V to 4.8 V.

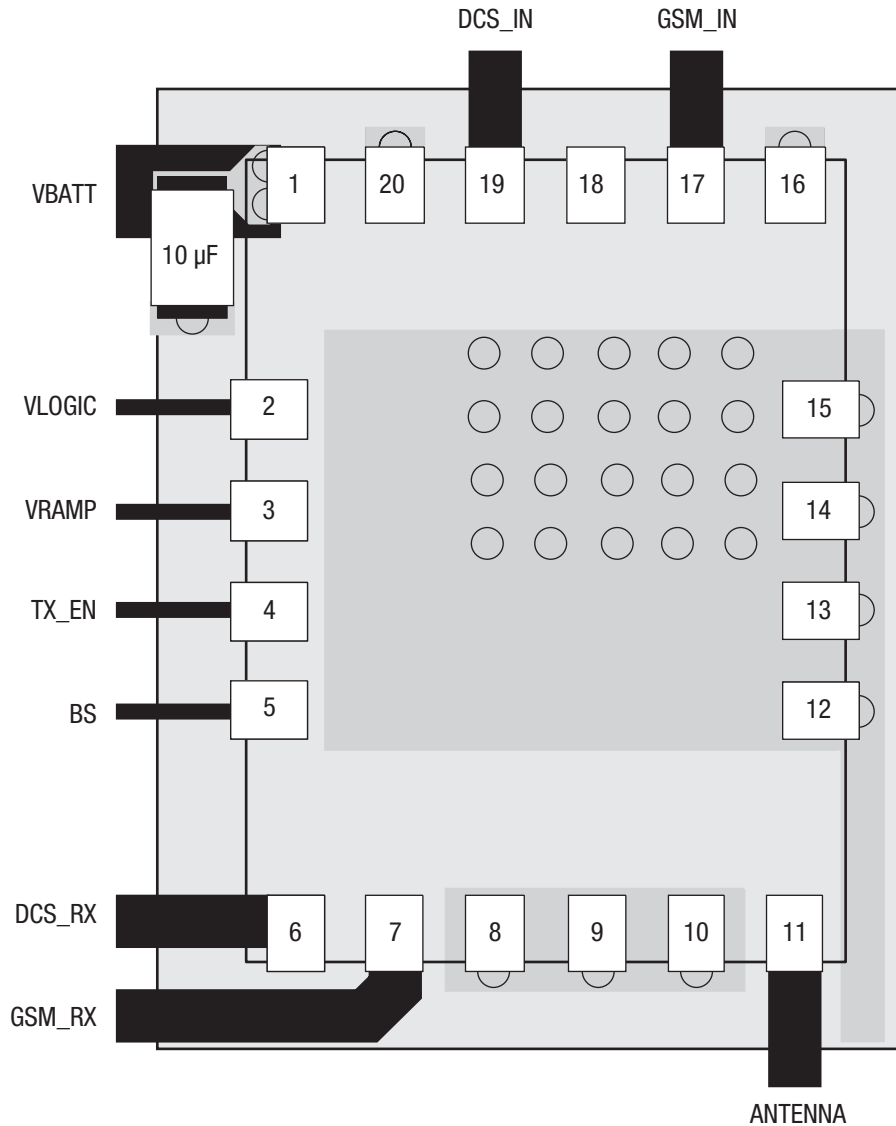
² ICC = 0A to xA, where x = current at P_{OUT} = 33 dBm, 50 Ω load, and V_{CC} = 3.3 V.

³ ICC = 0A to xA, where x = current at P_{OUT} = 31 dBm, 50 Ω load, and V_{CC} = 3.3 V

⁴ Terminate all unused RF ports with 50 Ω loads

⁵ Max V_{RAMP} = V_{RAMP} @ P_{OUT} =31 dBm, 50 Ω load, T_{CASE} +25 °C, P_{IN} = 3 dBm

⁶ Max V_{RAMP} = V_{RAMP} @ P_{OUT} =33 dBm, 50 Ω load, T_{CASE} +25 °C, P_{IN} = 3 dBm



NOTES:

1. The value of 10 µF cap is dependent on the noise level on the phone board.
2. Ensure sufficient number of vias to supply battery current to Vbatt.
3. VBATT trace width should be ≥ 1 mm.
4. Ground terminal of bypass capacitor connected to ground plane with vias.
5. Layer 2 should be solid ground plane under SKY77518 and any RF trace interconnect.

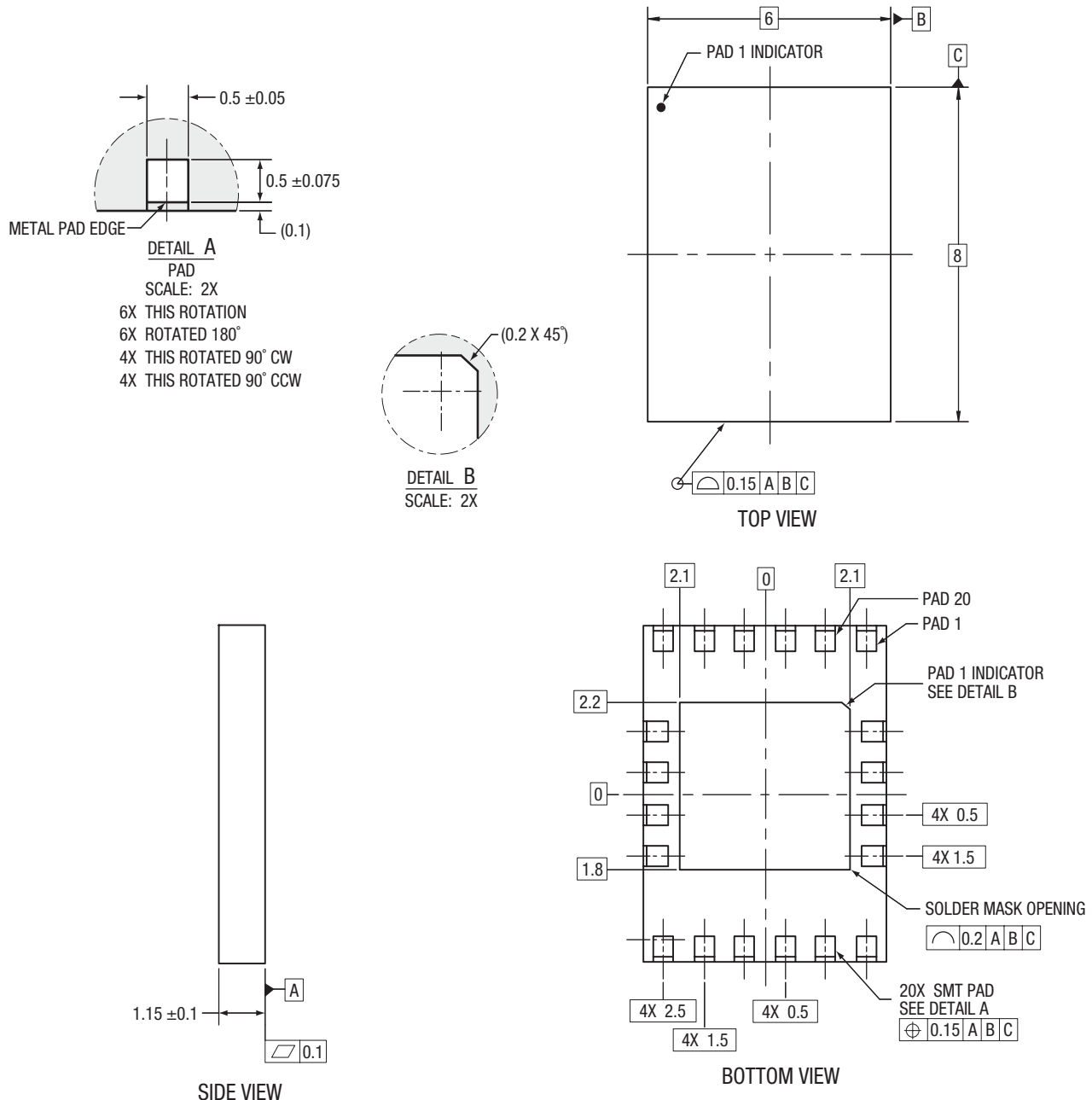
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Figure 2. SKY77518 Application Schematic Diagram

Package Dimensions and Pad Descriptions

Figure 3 is a mechanical diagram of the pad layout for the SKY77518, a 20-pad leadless dual-band FEM. Figure 4 provides a recommended phone board layout footprint for the FEM to help the designer attain optimum thermal conductivity, good grounding, and minimum RF discontinuity for the 50-ohm

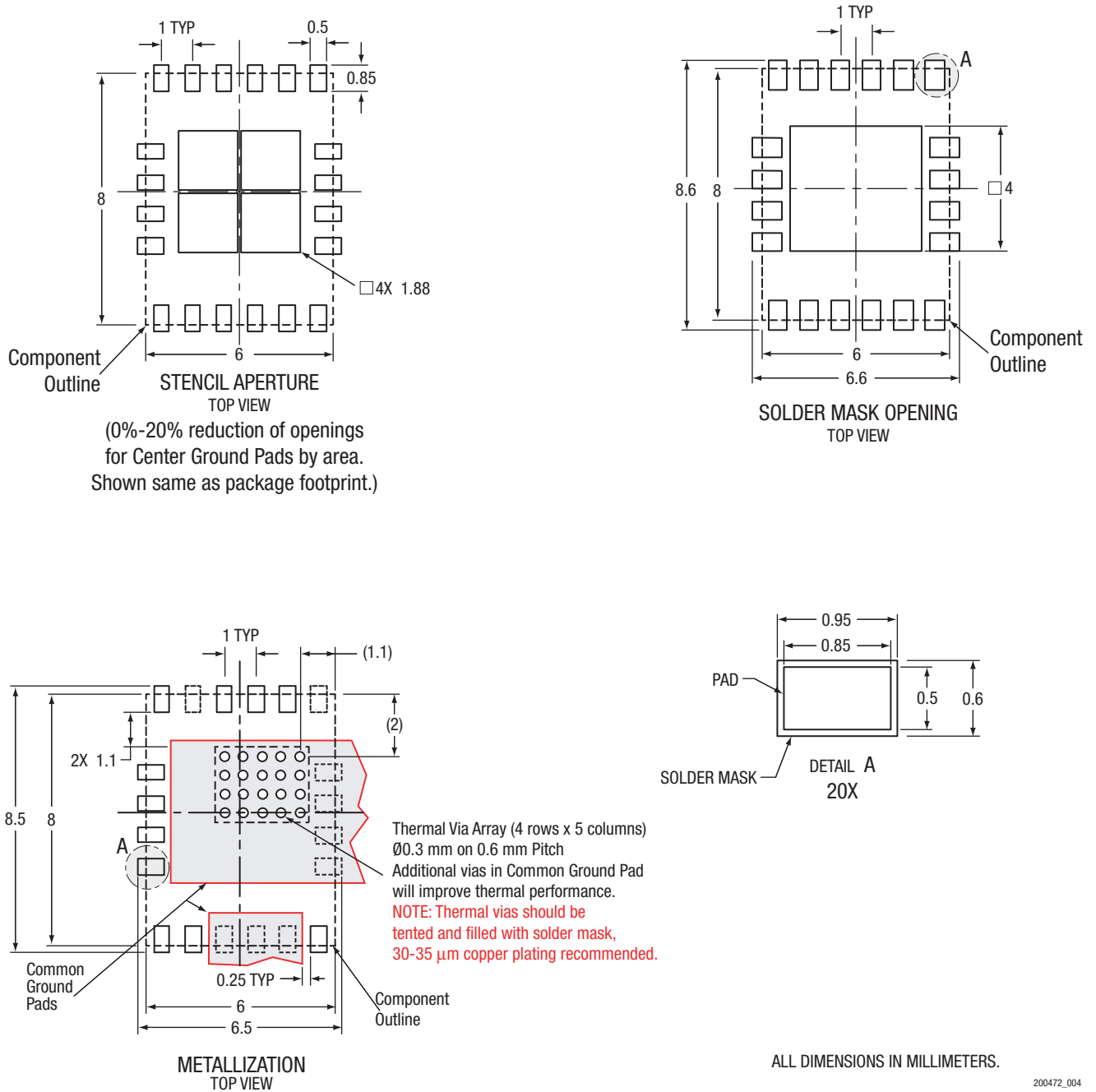
terminals. Figure 5 illustrates the device pad configuration and the numbering convention which starts with pad 1 at the upper left, as indicated, and increments counter-clockwise around the package. Table 5 lists the pad names and the associated signal descriptions. Figure 6 interprets typical case markings.



- NOTES: UNLESS OTHERWISE SPECIFIED.
1. Dimensioning and Tolerancing in accordance with ASME Y14.5-1994.
 2. Pads are solder mask defined on 3 edges.
 3. All dimensions are in millimeters.

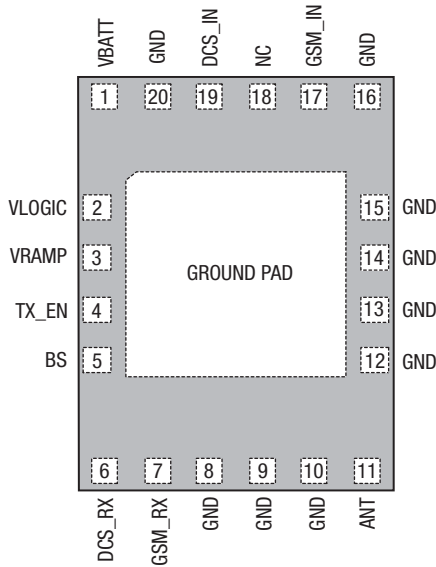
Figure 3. SKY77518 FEM Package Dimensions – 20-Pad Leadless (All Views)

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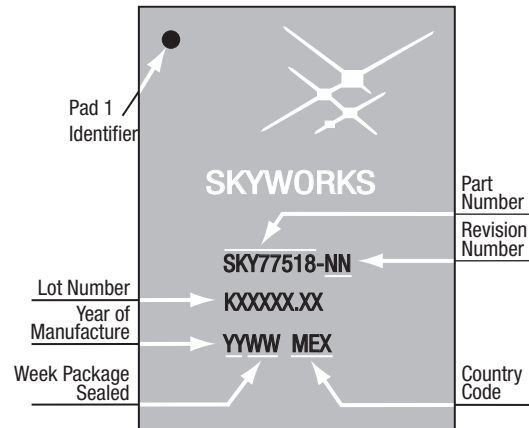
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Figure 4. Phone PCB Layout Footprint for 6 x 8 mm, 20-Pad Package with Grid-Bottom Solder Mask – SKY77518 Specific.



Pin layout as seen from top view looking through the package.

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200472_006

Figure 5. SKY77518 FEM Package Pad Configuration – 20-Pad Leadless (Top View)

Figure 6. Typical Case Markings

Table 5. SKY77518 Pad Names and Signal Descriptions

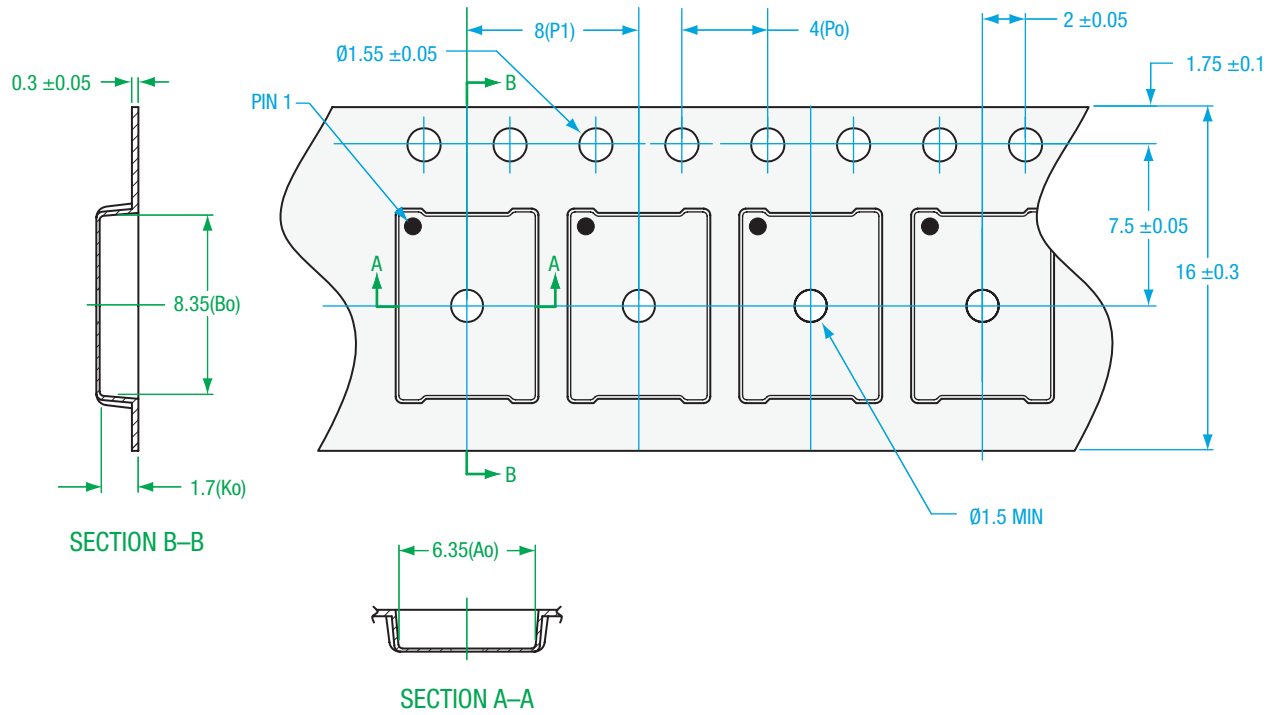
Pad	Name	Description
1	VBATT	Battery input voltage
2	VLOGIC	Control logic level selection/Standby control
3	VRAMP	Analog power control voltage input
4	TX_EN	TX / RX select (mode control)
5	BS	Band Select (mode control)
6	DCS_RX	DCS Receive RF Output (1805-1880 MHz)
7	GSM_RX	GSM Receive RF Output (920-960 MHz)
8	GND	RF and DC Ground
9	GND	RF and DC Ground
10	GND	RF and DC Ground
11	ANT	RF_IN / RF_OUT to Antenna
12	GND	RF and DC Ground
13	GND	RF and DC Ground
14	GND	RF and DC Ground
15	GND	RF and DC Ground
16	GND	RF and DC Ground
17	GSM_IN	RF input 880–915 MHz
18	NC	No Connect
19	DCS_IN	RF input 1710–1785 MHz
20	GND	RF and DC Ground
GND PADS	GROUND GRID	Ground Pads, module underside

Package and Handling Information

Because of its sensitivity to moisture absorption, this device package is baked and vacuum-packed prior to shipment. Instructions on the shipping container label must be followed regarding exposure to moisture after the container seal is broken, otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY77518 is capable of withstanding an MSL3/250 °C solder reflow. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. If the part is attached in a reflow oven, the temperature ramp rate should not exceed 3 °C per second; maximum temperature should not exceed 250 °C. If the part is manually attached, precaution should be taken to insure that the part is not subjected to temperatures exceeding 250 °C for more than 10 seconds. For details on attachment techniques, precautions, and handling procedures recommended by Skyworks, please refer to Skyworks Application Note: *PCB Design and SMT Assembly/Rework*, Document Number 101752. Additional information on standard SMT reflow profiles can also be found in the JEDEC *Joint Industry Standard J-STD-020*.

Production quantities of this product are shipped in the standard tape-and-reel format (see Figure 7). For additional packaging details, refer to Skyworks Application Note: *Tape and Reel Information – RF Modules*, Document Number 101568.



NOTES:

1. CARRIER TAPES MUST MEET ALL REQUIREMENTS OF SKYWORKS GP01-D232 PROCUREMENT SPEC FOR TAPE AND REEL SHIPPING.
- ② CARRIER TAPE SHALL BE BLACK CONDUCTIVE POLYSTYRENE.
3. COVER TAPE SHALL BE TRANSPARENT CONDUCTIVE PRESSURE SENSITIVE ADHESIVE (PSA) MATERIAL W/13.3 mm WIDTH.
4. ESD-SURFACE RESISTIVITY SHALL BE $\leq 1 \times 10^{10}$ OHMS/SQUARE PER EIA, JEDEC TNR SPECIFICATION.
5. Po/P1, 10 PITCHES CUMULATIVE TOLERANCE ON TAPE: ± 0.2 mm.
6. Ao & Bo MEASUREMENT POINT TO BE 0.3 mm FROM BOTTOM POCKET.
7. ALL DIMENSIONS ARE IN MILLIMETERS.
8. PART NO.: eC3-MCM0608-16-8-F1-L REV. 0. PLEASE INDICATE ON PURCHASE ORDER.
9. NUMBER OF PARTS per 13 inch (DIAMETER) x 16 mm wide REEL: 2500.

ePAK CARRIER TAPE

CARRIER TAPE_OVERMOLD MCM_6x8x1.4 mm BODY SIZE_GP01-D232-081B
101568_011

Figure 7. Tape and Reel Dimensional Diagram for 6 x 8 x 1.2 mm Package SKY77518 Specific

Electrostatic Discharge Sensitivity

The SKY77518 is a Class I device. The ESD testing was performed in compliance with IEC 61000-4-2 requirements.

Various failure criteria can be utilized when performing ESD testing. Many vendors employ relaxed ESD failure standards that fail devices only after “the pad fails the electrical specification limits” or “the pad becomes completely non-functional”.

Skyworks employs stringent criteria, rejecting devices as soon as the pad begins to show any degradation on a curve tracer.

To avoid ESD damage, both latent and visible, it is very important that the product assembly and test areas follow the Class-1 ESD handling precautions listed in [Table 6](#).

Table 6. Precautions for Handling GaAs IC-Based Products to Avoid Induced Damage

Personnel Grounding	Wrist Straps Conductive Smocks, Gloves and Finger Cots Antistatic ID Badges
Facility	Relative Humidity Control and Air Ionizers Dissipative Floors (less than 10 ⁹ to GND)
Protective Workstation	Dissipative Table Tops Protective Test Equipment (Properly Grounded) Grounded Tip Soldering Irons Conductive Solder Suckers Static Sensors
Protective Packaging and Transportation	Bags and Pouches (Faraday Shield) Protective Tote Boxes (Conductive Static Shielding) Protective Trays Grounded Carts Protective Work Order Holders

Ordering Information

Model Number	Manufacturing Part Number	Product Revision	Package	Operating Temperature
SKY77518	SKY77518		6x8MCM-20	-20 °C to +100 °C

Revision History

Revision	Level	Date	Description
P1		November 9, 2005	Initial Issue – Preliminary Information
P2		July 12, 2006	Revise: Features list (p1); Tables 2, 4
P3		August 3, 2006	Revise: Figure 1; Table 4

References

Application Note: PCB Design and SMT Assembly/Rework, Document Number 101752

Application Note: Tape and Reel Information – RF Modules, Document Number 101568

Standard SMT Reflow Profiles: JEDEC Standard J-STD-020

Application Note: BiCMOS iPAC™ Front-End Modules, Document Number 200129

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易迪拓培训(www.edatop.com)由数名来自于研发第一线的资深工程师发起成立,致力并专注于微波、射频、天线设计研发人才的培养;我们于 2006 年整合合并微波 EDA 网(www.mweda.com),现已发展成为国内最大的微波射频和天线设计人才培养基地,成功推出多套微波射频以及天线设计经典培训课程和 ADS、HFSS 等专业软件使用培训课程,广受客户好评;并先后与人民邮电出版社、电子工业出版社合作出版了多本专业图书,帮助数万名工程师提升了专业技术能力。客户遍布中兴通讯、研通高频、埃威航电、国人通信等多家国内知名公司,以及台湾工业技术研究院、永业科技、全一电子等多家台湾地区企业。

易迪拓培训课程列表: <http://www.edatop.com/peixun/rfe/129.html>



射频工程师养成培训课程套装

该套装精选了射频专业基础培训课程、射频仿真设计培训课程和射频电路测量培训课程三个类别共 30 门视频培训课程和 3 本图书教材;旨在引领学员全面学习一个射频工程师需要熟悉、理解和掌握的专业知识和研发设计能力。通过套装的学习,能够让学员完全达到和胜任一个合格的射频工程师的要求...

课程网址: <http://www.edatop.com/peixun/rfe/110.html>

ADS 学习培训课程套装

该套装是迄今国内最全面、最权威的 ADS 培训教程,共包含 10 门 ADS 学习培训课程。课程是由具有多年 ADS 使用经验的微波射频与通信系统设计领域资深专家讲解,并多结合设计实例,由浅入深、详细而又全面地讲解了 ADS 在微波射频电路设计、通信系统设计和电磁仿真设计方面的内容。能让您在最短的时间内学会使用 ADS,迅速提升个人技术能力,把 ADS 真正应用到实际研发工作中去,成为 ADS 设计专家...



课程网址: <http://www.edatop.com/peixun/ads/13.html>



HFSS 学习培训课程套装

该套课程套装包含了本站全部 HFSS 培训课程,是迄今国内最全面、最专业的 HFSS 培训教程套装,可以帮助您从零开始,全面深入学习 HFSS 的各项功能和在多个方面的工程应用。购买套装,更可超值赠送 3 个月免费学习答疑,随时解答您学习过程中遇到的棘手问题,让您的 HFSS 学习更加轻松顺畅...

课程网址: <http://www.edatop.com/peixun/hfss/11.html>

CST 学习培训课程套装

该培训套装由易迪拓培训联合微波 EDA 网共同推出,是最全面、系统、专业的 CST 微波工作室培训课程套装,所有课程都由经验丰富的专家授课,视频教学,可以帮助您从零开始,全面系统地学习 CST 微波工作的各项功能及其在微波射频、天线设计等领域的设计应用。且购买该套装,还可超值赠送 3 个月免费学习答疑...

课程网址: <http://www.edatop.com/peixun/cst/24.html>



HFSS 天线设计培训课程套装

套装包含 6 门视频课程和 1 本图书,课程从基础讲起,内容由浅入深,理论介绍和实际操作讲解相结合,全面系统的讲解了 HFSS 天线设计的全过程。是国内最全面、最专业的 HFSS 天线设计课程,可以帮助您快速学习掌握如何使用 HFSS 设计天线,让天线设计不再难...

课程网址: <http://www.edatop.com/peixun/hfss/122.html>

13.56MHz NFC/RFID 线圈天线设计培训课程套装

套装包含 4 门视频培训课程,培训将 13.56MHz 线圈天线设计原理和仿真设计实践相结合,全面系统地讲解了 13.56MHz 线圈天线的工作原理、设计方法、设计考量以及使用 HFSS 和 CST 仿真分析线圈天线的具体操作,同时还介绍了 13.56MHz 线圈天线匹配电路的设计和调试。通过该套课程的学习,可以帮助您快速学习掌握 13.56MHz 线圈天线及其匹配电路的原理、设计和调试...

详情浏览: <http://www.edatop.com/peixun/antenna/116.html>



我们的课程优势:

- ※ 成立于 2004 年,10 多年丰富的行业经验,
- ※ 一直致力并专注于微波射频和天线设计工程师的培养,更了解该行业对人才的要求
- ※ 经验丰富的一线资深工程师讲授,结合实际工程案例,直观、实用、易学

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